

# Chemicals contained in products

## Package-type

Epson Package name; **TQFP14-80PIN / Halogen free**

JEITA Package name; **P-TQFP080-1212-0.50**

Lead frame plating; **Lead(Pb) Free**

Weight; **0.40 [g]** \*Note1

Part	Subpart	Subpart weight [mg]	Substance name	CAS No.	Content *Note2		Application
					[mg]	[ppm]	
IC Die	IC Die	2.8	Silicon	7440-21-3	2.8	999894	Base material
			Boron	7440-42-8	0.000006	2	Dopant
			Phosphorus	7723-14-0	0.00001	5	Dopant
			Aluminum	7429-90-5	0.00006	20	Metalization
			Arsenic *Note3	7440-38-2	0.00001	5	Dopant
			Fluorine *Note3	7782-41-4	0.000006	2	Dopant
			Titanium *Note3	7440-32-6	0.00006	20	Metalization
			Molybdenum *Note3	7439-98-7	0.00006	20	Metalization
			Tungsten *Note3	7440-33-7	0.00008	30	Metalization
			Cobalt *Note3	7440-48-4	0.000006	2	Metalization
	Stress buffer coat	0.06	Polyimide	-	0.06	1000000	Stress buffer coat *Note4
Package	Die Bonding material	0.72	Silver	7440-22-4	0.66	910000	Base material
			Acrylic resin	-	0.05	70000	Adhesive
			Epoxy resin	-	0.01	20000	Adhesive
	Lead Frame Plating	2.27	Tin	7440-31-5	2.27	1000000	Solder
	Lead Frame	158.28	Copper	7440-50-8	149.57	945000	Conductor
			Silver	7440-22-4	0.79	5000	Inner lead plating
			Others *Note5	-	7.91	50000	Additive
	Bonding Wire	1.88	Gold	7440-57-5	1.88	1000000	Conductor
	Mold resin	234.00	Epoxy resin	-	14.74	63000	Base material
			Silica	60676-86-0/-	205.92	880000	Filler
			Carbon black	1333-86-4	0.47	2000	Coloring agent
			Hardening chemical(ex:Phenol resin)	-	9.36	40000	Base material
			Organic phosphorous compound	-	1.17	5000	Hardening accelerator
			others	-	2.34	10000	Additive

Regarding the information of chemical substances

\*Note1 The weight might be somewhat different depending on an individual built-in IC-chip specification like the size etc.

\*Note2 Content data are estimated values based on supplier information and intended levels of content in product.

Actual measurements may vary from these values somewhat.

\*Note3 Use or not-use of these substances depends on individual built-in IC-chip specification.

\*Note4 The stress buffer coat may not be used depending on the individual model.

\*Note5 The nickel, zinc, tin, silicon, iron, and the zinc oxide are included.